DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$ max	I_D max T_A = 25°C
60V	7.5Ω @ V_{GS} = 5V	0.23A

Features and Benefits

- Dual N-Channel MOSFET
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- **Totally Lead-Free & Fully RoHS compliant (Note 1)**
- **Halogen and Antimony Free. "Green" Device (Note 2 and 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor control
- Power Management Functions

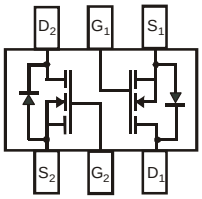
Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)

SOT363



Top View



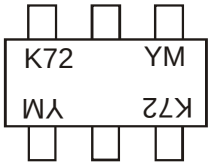
Top View
Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
2N7002DW-7-F	SOT363	3,000/Tape & Reel
2N7002DW-13-F	SOT363	10,000/Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
3. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb_2O_3 Fire Retardants.
4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



K72 = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: N = 2002)
M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	…	2011	2012	2013	2014	2015	2016	2017
Code	J	K	L	M	N	P	R	…	Y	Z	A	B	C	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	60	V
Drain-Gate Voltage $R_{GS} \leq 1.0M\Omega$			V_{DGR}	60	V
Gate-Source Voltage	Continuous		V_{GSS}	±20	V
	Pulsed		V_{GSS}	±40	V
Continuous Drain Current (Note 6) V_{GS} = 5V	Steady State	T_A = 25°C T_A = 70°C T_A = 100°C	I_D	0.23 0.18 0.14	A
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	0.53	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I_{DM}	0.8	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T_A = 25°C	P_D	0.31	W
	T_A = 70°C		0.2	
	T_A = 100°C		0.12	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	$R_{\theta JA}$	410	°C/W
Total Power Dissipation (Note 6)	T_A = 25°C	P_D	0.4	W
	T_A = 70°C		0.25	
	T_A = 100°C		0.15	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	$R_{\theta JA}$	318	°C/W
Thermal Resistance, Junction to Case (Note 6)	Steady state	$R_{\theta JC}$	135	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage		BV_{DSS}	60	70	—	V	V_{GS} = 0V, I_D = 10µA
Zero Gate Voltage Drain Current	@ T_C = 25°C @ T_C = 125°C	I_{DSS}	—	—	1.0 500	µA	V_{DS} = 60V, V_{GS} = 0V
Gate-Body Leakage		I_{GSS}	—	—	±10	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage		$V_{GS(th)}$	1.0	—	2.0	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	@ T_J = 25°C	$R_{DS\ (ON)}$	—	3.2	7.5	Ω	V_{GS} = 5.0V, I_D = 0.05A
	@ T_J = 125°C			4.4	13.5		V_{GS} = 10V, I_D = 0.5A
On-State Drain Current		$I_{D(ON)}$	0.5	1.0	—	A	V_{GS} = 10V, V_{DS} = 7.5V
Forward Transconductance		g_{FS}	80	—	—	mS	V_{DS} =10V, I_D = 0.2A
Diode Forward Voltage		V_{SD}	—	0.78	1.5	V	V_{GS} = 0V, I_S = 115mA
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance		C_{iss}	—	22	50	pF	V_{DS} = 25V, V_{GS} = 0V f = 1.0MHz
Output Capacitance		C_{oss}	—	11	25	pF	
Reverse Transfer Capacitance		C_{rss}	—	2.0	5.0	pF	
SWITCHING CHARACTERISTICS (Note 8)							
Turn-On Delay Time		$t_{D(on)}$	—	7.0	20	ns	V_{DD} = 30V, I_D = 0.2A, R_L = 150Ω, V_{GEN} = 10V, R_{GEN} = 25Ω
Turn-Off Delay Time		$t_{D(off)}$	—	11.0	20		

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

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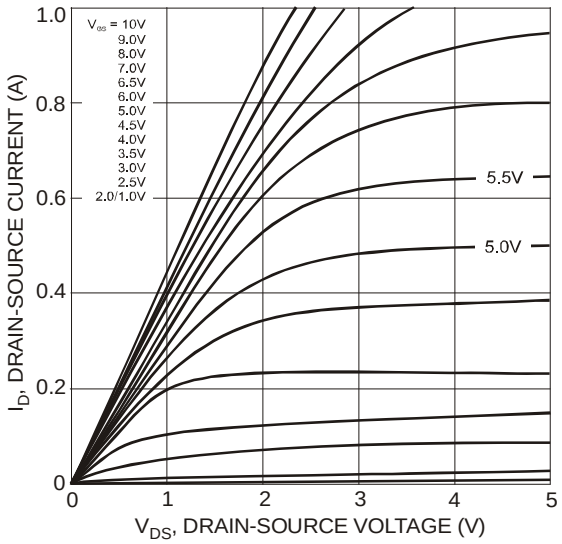


Fig. 1 On-Region Characteristics

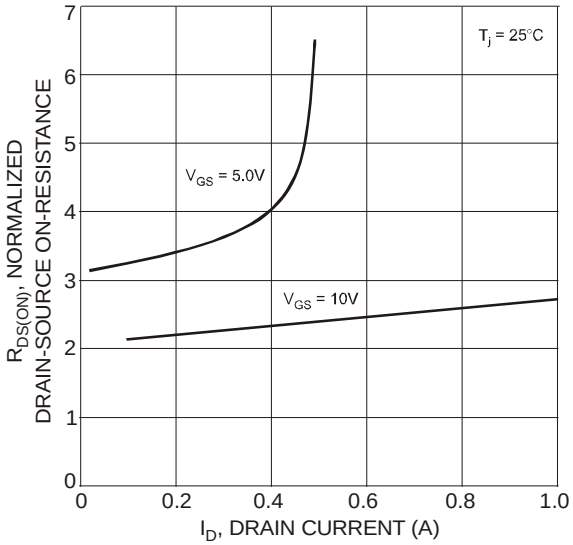


Fig. 2 On-Resistance vs. Drain Current

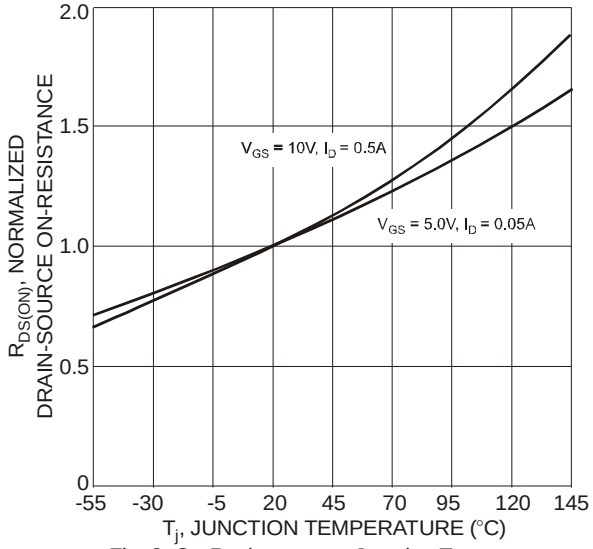


Fig. 3 On-Resistance vs. Junction Temperature

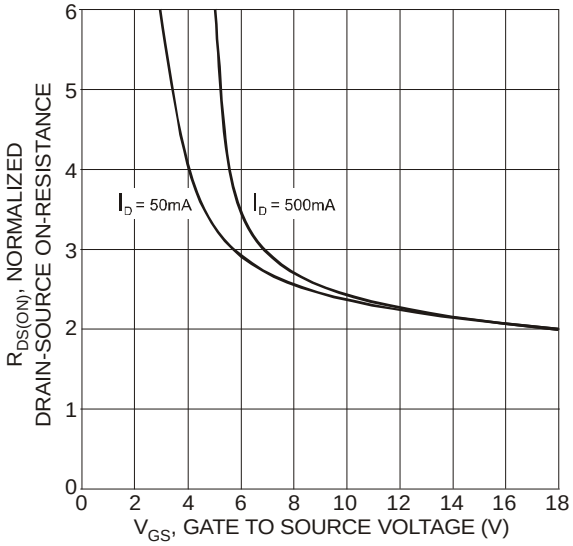
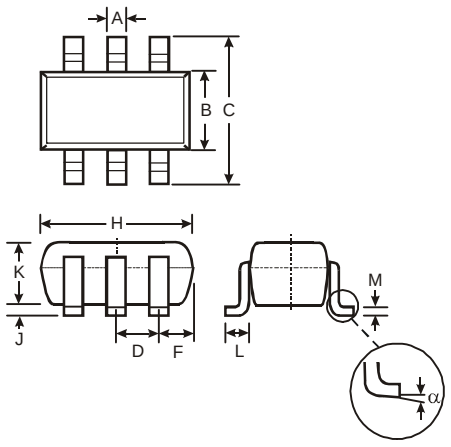


Fig. 4 On-Resistance vs. Gate-Source Voltage

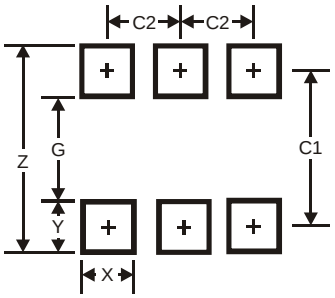
Package Outline Dimensions



SOT363		
Dim	**Min**	**Max**
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

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Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

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